IPC ASSOCIATION CONNECTED ELECTRONICS INDUSTRI	Material Compo © Copyright 2005. If international and Pan	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mf	g Informat	ion	
upplier Infor										,					
Company name*		Company unique ID			τ	Unique ID Authority					Response Date*				
onsemi											2025-06-08				
Contact Name		Title - Contact			1	Phone - Contact*					Email - Contact*				
Product-Env-Ste	wards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
uthorized Repre	esentative*	Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-Env-Ste	wards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
Reque	Requester Item Number Mfr		Item Number Mfr Item Name				Effective Dat	te Ver	sion	Manufacturing Site		V	/eight*	UOM	Unit Type
		ESD7016MUTAG Low		Low CAP TVS for USB 3		2025-06-08				1	4.83	mg	Each		
Ianufacturin	g Proccess Informat	tion						<u> </u>							
Terminal Plating / Grid Array Material To			Terminal Base Alloy J-STD-020 MSI		L Rating	Peak Process Body Temperate		ıre Max Tin	ne at Peak	Temperatu	re Num	ber of Reflow Cyc	eles		
Matte Tin (Sn) - annealed		CU Alloy 1			260		С	C 30		seconds 3					
omments															
vel 1 - maximun	n time at peak temperatu	re during sol	dering is 10-3	30 seconds											
or more informa	tion regarding material	composition	please refer t	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.98	mg	Supplier	Silicon (Si)	7440-21-3		0.98	mg
Die Attach Epoxy	0.18	mg		Epoxy resin	proprietary data		0.018	mg
			Supplier	Cumene hydroperoxide	80-15-9		0.0009	mg
			Supplier	Diethylene glycol monoethyl ether acetate	112-15-2		0.0081	mg
			Supplier	Silver (Ag)	7440-22-4		0.153	mg
Lead Frame	4.0	mg	Supplier	Tin (Sn)	7440-31-5		0.01	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0088	mg
			Supplier	Chromium (Cr)	7440-47-3		0.01	mg
			Supplier	Copper (Cu)	7440-50-8		3.9712	mg
Lead Frame plating	0.03	mg	Supplier	Silver (Ag)	7440-22-4		0.03	mg
Mold Compound-Black	8.09	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.6472	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0404	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.1618	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.9979	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.2427	mg
Plating	1.41	mg	Supplier	Tin (Sn)	7440-31-5		1.41	mg
Wire Bond - Au	0.14	mg	Supplier	Gold (Au)	7440-57-5		0.14	mg